

N-channel 30 V, 0.021 Ω typ., 6 A STripFET™ H6 Power MOSFET in a PowerFLAT™ 2x2 package

Datasheet - production data

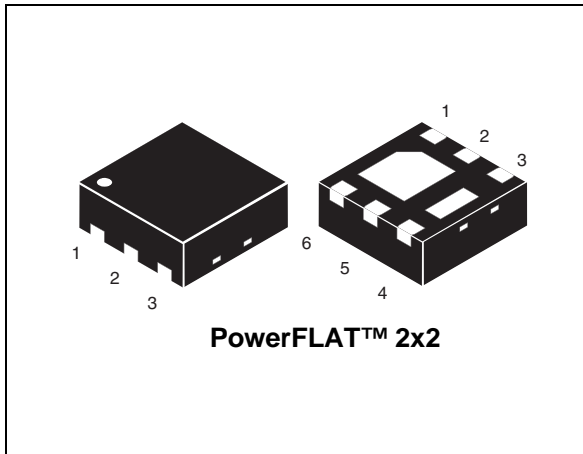
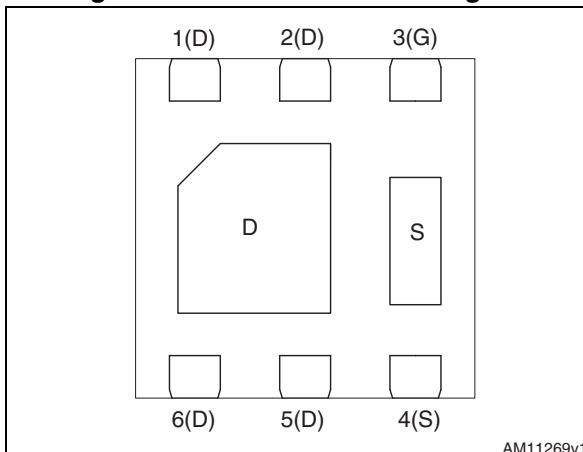


Figure 1. Internal schematic diagram



Features

| Order code | V _{DS} | R _{DS(on)} max | I _D | P _{TOT} |
|------------|-----------------|---|----------------|------------------|
| STL6N3LLH6 | 30 V | 0.025 Ω (V _{GS} =10 V) 0.04 Ω (V _{GS} = 4.5 V) | 6 A | 2.4 W |

- Very low on-resistance
- Very low gate charge
- High avalanche ruggedness
- Low gate drive power loss

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using the STripFET™ H6 technology, with a new trench gate structure. The resulting Power MOSFET exhibits very low R_{DS(on)} in all packages.

Table 1. Device summary

| Order code | Marking | Package | Packaging |
|------------|---------|----------------|---------------|
| STL6N3LLH6 | STG1 | PowerFLAT™ 2x2 | Tape and reel |

Contents

| | | |
|----------|---|-----------|
| 1 | Electrical ratings | 3 |
| 2 | Electrical characteristics | 4 |
| | 2.1 Electrical characteristics (curves) | 6 |
| 3 | Test circuits | 8 |
| 4 | Package information | 9 |
| 5 | Revision history | 12 |

1 Electrical ratings

Table 2. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|-------------------|---|------------|------------------|
| V_{DS} | Drain-source voltage | 30 | V |
| V_{GS} | Gate-source voltage | ± 20 | V |
| $I_D^{(1)}$ | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$ | 13 | A |
| $I_D^{(1)}$ | Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$ | 8.2 | A |
| $I_{DM}^{(1)(2)}$ | Drain current (pulsed) | 52 | A |
| $I_D^{(3)}$ | Drain current (continuous) at $T_{pcb} = 25\text{ }^\circ\text{C}$ | 6 | A |
| $I_D^{(3)}$ | Drain current (continuous) at $T_{pcb} = 100\text{ }^\circ\text{C}$ | 3.75 | A |
| $I_{DM}^{(2)(3)}$ | Drain current (pulsed) | 24 | A |
| $P_{TOT}^{(1)}$ | Total dissipation at $T_C = 25\text{ }^\circ\text{C}$ | 7.8 | W |
| $P_{TOT}^{(3)}$ | Total dissipation at $T_{pcb} = 25\text{ }^\circ\text{C}$ | 2.4 | |
| T_J | Operating junction temperature | -55 to 150 | $^\circ\text{C}$ |
| T_{stg} | Storage temperature | | |

1. This value is rated according to $R_{thj-case}$
2. Pulse width limited by safe operating area
3. This value is rated according to $R_{thj-pcb}$

Table 3. Thermal resistance

| Symbol | Parameter | Value | Unit |
|---------------------|--------------------------------------|-------|---------------------------|
| $R_{thj-pcb}^{(1)}$ | Thermal resistance junction-pcb | 52 | $^\circ\text{C}/\text{W}$ |
| $R_{thj-case}$ | Thermal resistance junction-case max | 16 | $^\circ\text{C}/\text{W}$ |

1. When mounted on FR-4 board of 1inch², 2oz Cu, $t < 10\text{ sec}$

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified).

Table 4. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|-----------------------------------|---|------|-------|-----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $I_D = 250\ \mu\text{A}$, $V_{GS} = 0\ \text{V}$ | 30 | | | V |
| I_{DSS} | Zero gate voltage drain current | $V_{DS} = 30\ \text{V}$, $V_{GS} = 0$ | | | 1 | μA |
| | | $V_{DS} = 30\ \text{V}$, $T_C = 125\text{ °C}$ ($V_{GS} = 0$) | | | 10 | μA |
| I_{GSS} | Gate body leakage current | $V_{GS} = \pm 20\ \text{V}$, ($V_{DS} = 0$) | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{A}$ | 1 | | | V |
| $R_{DS(on)}$ | Static drain-source on-resistance | $V_{GS} = 10\ \text{V}$, $I_D = 3\ \text{A}$ | | 0.021 | 0.025 | Ω |
| | | $V_{GS} = 4.5\ \text{V}$, $I_D = 3\ \text{A}$ | | 0.032 | 0.04 | Ω |

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------|------------------------------|--|------|------|------|------|
| C_{iss} | Input capacitance | $V_{DS} = 24\ \text{V}$, $f = 1\ \text{MHz}$, ($V_{GS} = 0$) | - | 283 | - | pF |
| C_{oss} | Output capacitance | | - | 61 | - | |
| C_{rss} | Reverse transfer capacitance | | - | 31 | - | |
| Q_g | Total gate charge | $V_{DD} = 15\ \text{V}$, $I_D = 6\ \text{A}$ $V_{GS} = 4.5\ \text{V}$ (see Figure 14.: Gate charge test circuit) | - | 3.6 | - | nC |
| Q_{gs} | Gate-source charge | | - | 1.5 | - | |
| Q_{gd} | Gate-drain charge | | - | 1.1 | - | |

Table 6. Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on delay time | $V_{DD} = 10\ \text{V}$, $I_D = 6\ \text{A}$, $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\ \text{V}$ (see Figure 13.: Switching times test circuit for resistive load) | - | 4.8 | - | ns |
| t_r | Rise time | | - | 11.2 | - | |
| $t_{d(off)}$ | Turn-off delay time | | - | 9.4 | - | |
| t_f | Fall time | | - | 5.4 | - | |

Table 7. Source drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------|--------------------------|---|------|------|------|------|
| $V_{SD}^{(1)}$ | Forward on voltage | $I_{SD} = 6 \text{ A}$, $V_{GS} = 0 \text{ V}$ | - | | 1.1 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 6 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$, $V_{DD} = 16 \text{ V}$, $T_J = 150 \text{ }^\circ\text{C}$ | - | 10.6 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 2.8 | | nC |
| I_{RRM} | Reverse recovery current | | - | 0.5 | | A |

1. Pulsed: pulse duration=300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

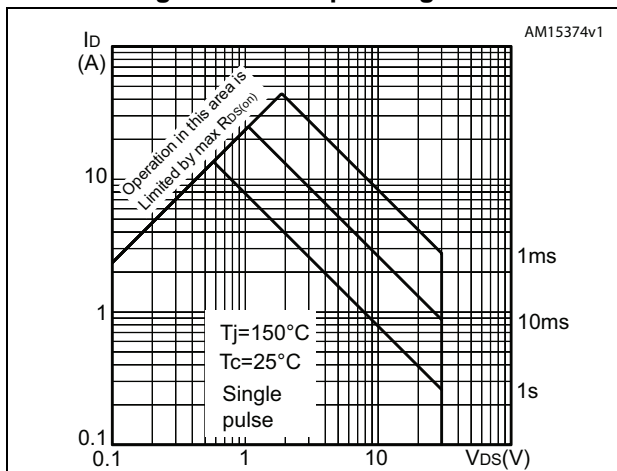


Figure 3. Thermal impedance

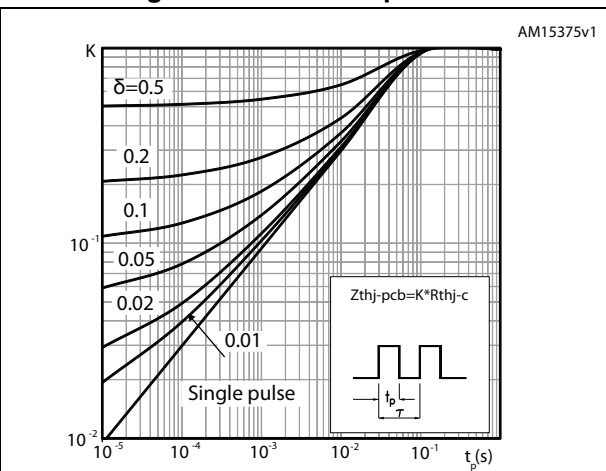


Figure 4. Output characteristics

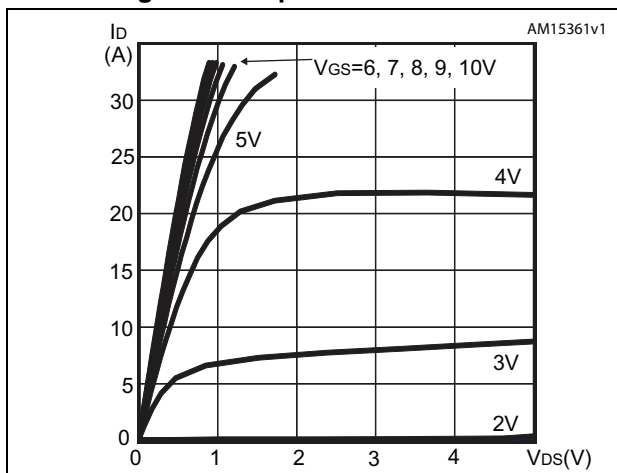


Figure 5. Transfer characteristics

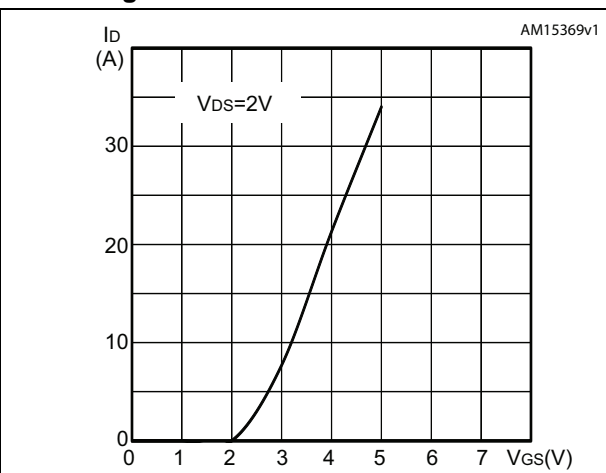


Figure 6. Gate charge vs gate-source voltage

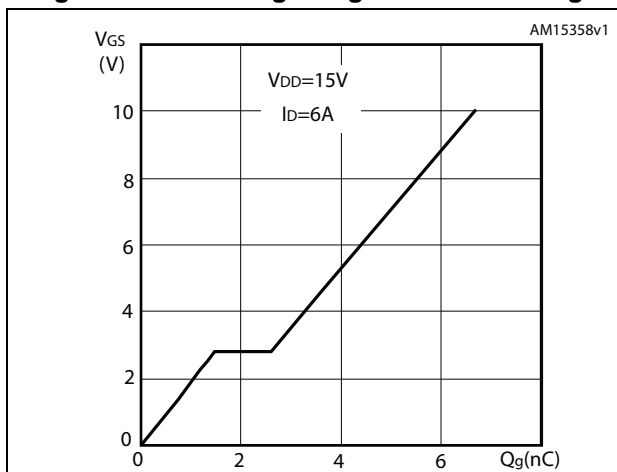


Figure 7. Static drain-source on-resistance

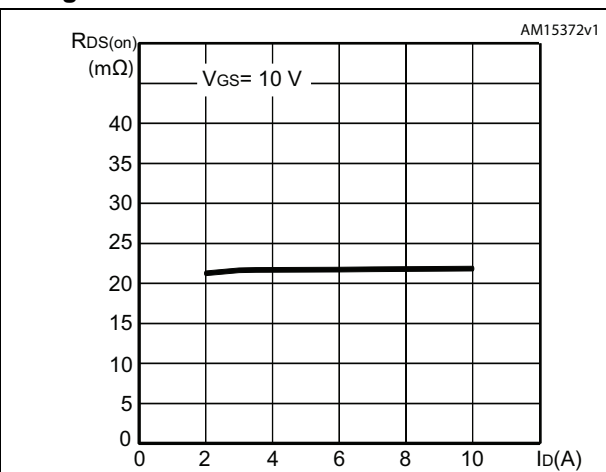


Figure 8. Capacitance variations

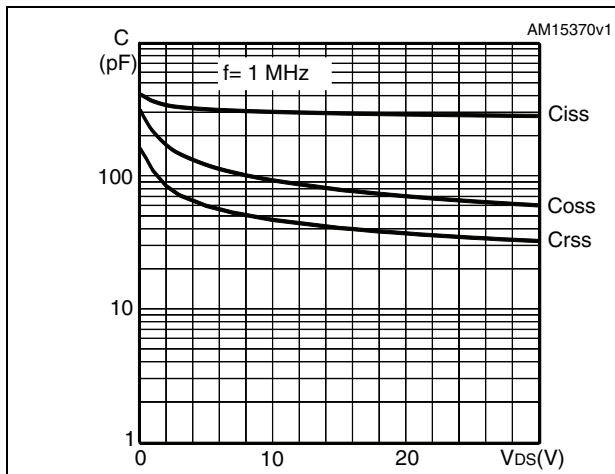


Figure 9. Normalized on-resistance vs temperature

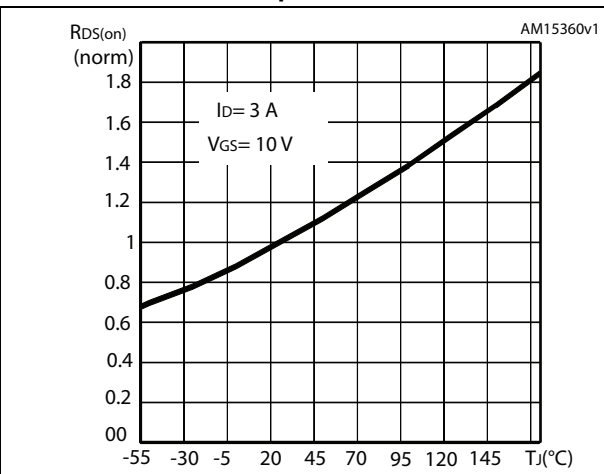


Figure 10. Normalized gate threshold voltage vs temperature

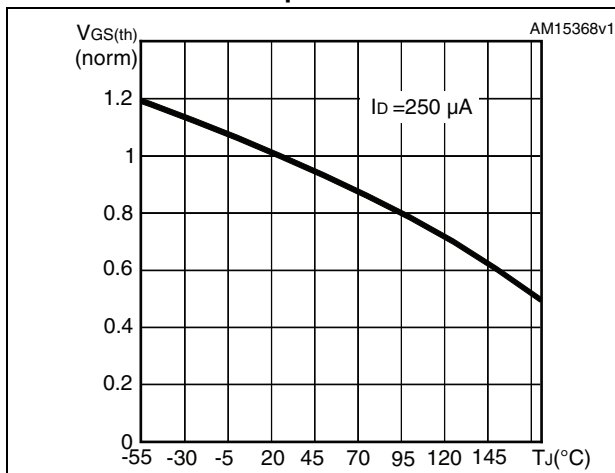


Figure 11. Normalized V(BR)DSS vs temperature

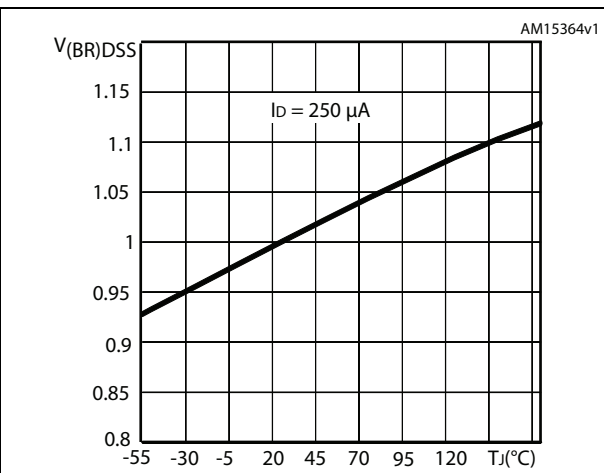
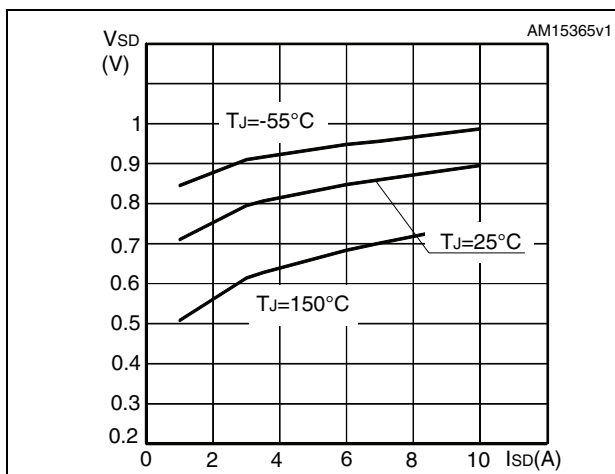


Figure 12. Source-drain diode forward characteristics



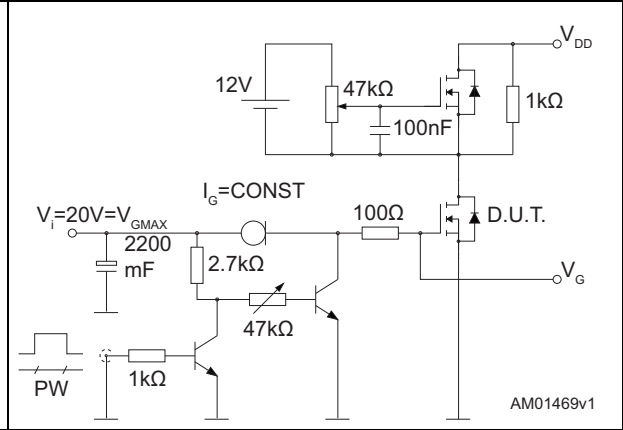
3 Test circuits

Figure 13. Switching times test circuit for resistive load



AM01468v1

Figure 14. Gate charge test circuit



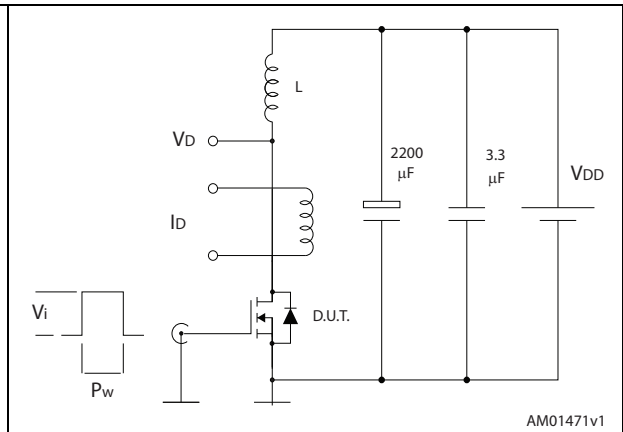
AM01469v1

Figure 15. Test circuit for inductive load switching and diode recovery times



AM01470v1

Figure 16. Unclamped inductive load test circuit



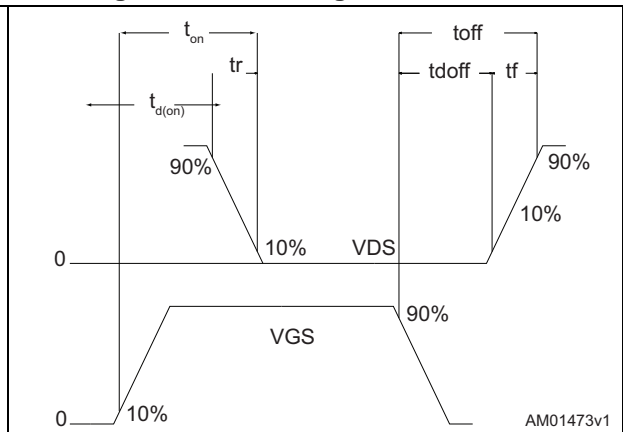
AM01471v1

Figure 17. Unclamped inductive waveform



AM01472v1

Figure 18. Switching time waveform

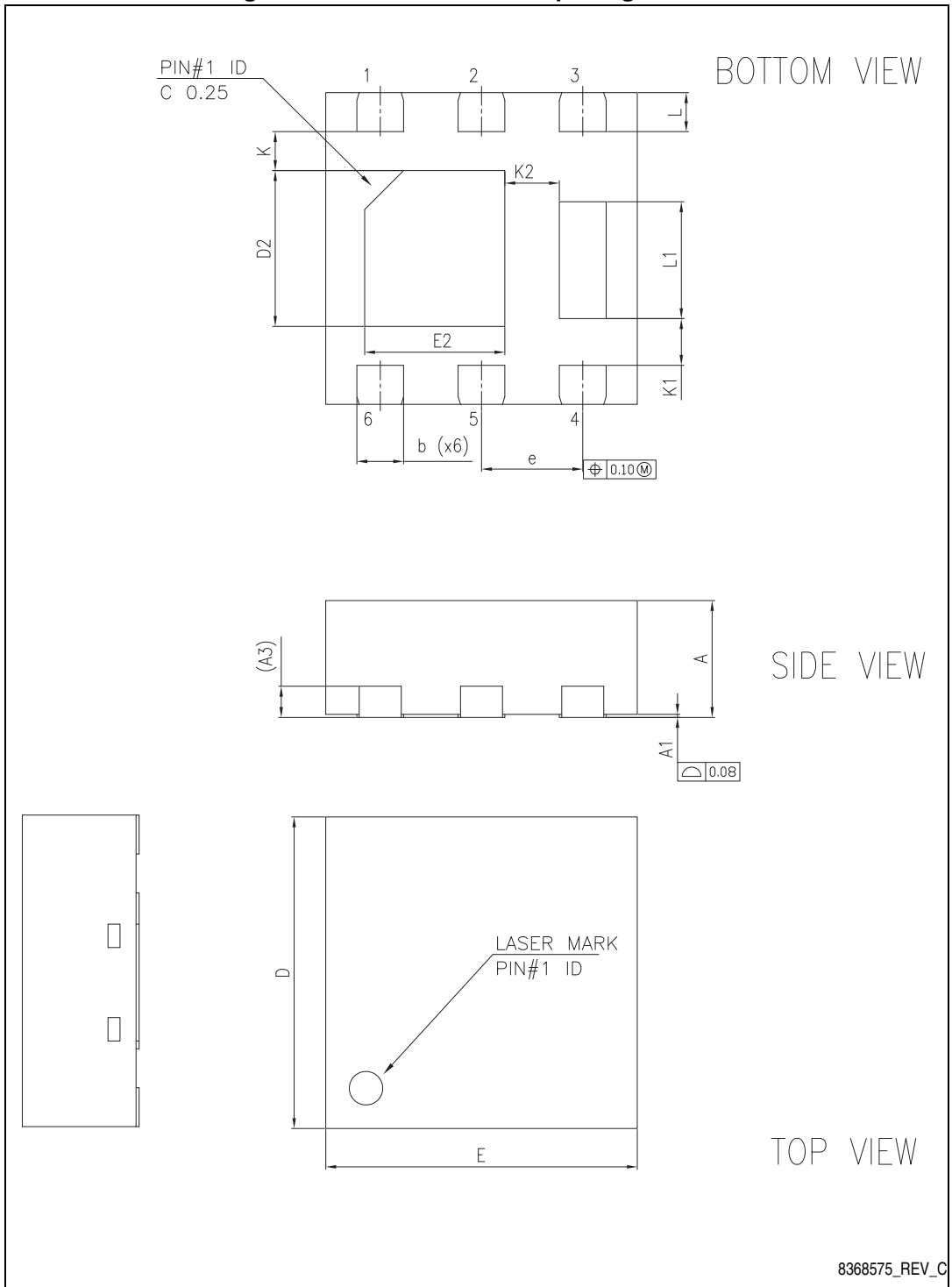


AM01473v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 19. PowerFLAT™ 2 x 2 package outline



5 Revision history

Table 10. Document revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 25-May-2012 | 1 | First release |
| 11-Oct-2012 | 2 | <ul style="list-style-type: none">– Added Section 2.1: Electrical characteristics (curves).– $R_{DS(on)}$ values (typ. and max.) updated– Typical values updated in Table 5, 6 and 7– Minor text changes. |
| 21-Oct-2015 | 3 | <ul style="list-style-type: none">– Updated title and description in cover page.– Datasheet promoted from preliminary data to production data.– Updated Table 2, Table 4, Table 5 and Table 7.– Updated Figure 6 and Figure 7.– Minor text changes. |

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2015 STMicroelectronics – All rights reserved

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[STMicroelectronics:](#)

[STL6N3LLH6](#)